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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10036389	01/07/2002	257		813 2811	

**APPLICANTS: Liu Cheng-Yi; Swan Johanna; Towle Steven;

**CONTINUING DATA VERIFIED: none yet

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** FOREIGN APPLICATIONS VERIFIED: none yet

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 2207/12660
Verified and Acknowledged Examiners's initials			
TITLE : Thinned die integrated circuit package			
U.S. DEPT. OF COMM /PAT. & TM-PTO-436 (Rev. 12-91)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg. Figs.Drwg. Print Fig.		
		Primary Examiner		
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		
Application Examiner				
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